09/777,725

=> d l8 bib abs 1-8

L8 ANSWER 1 OF 8 USPATFULL on STN
AN 2003:297111 USPATFULL
TI Conductive structures
IN Lussey, David, Richmond, UNITED KINGDOM
PA Peratech Limited, Darlington, UNITED KINGDOM (non-U.S. corporation)
PI US 6646540 B1 20031111
WO 2000079546 20001228
AI US 2001-18400 20011219 (10)
WO 2000-GB2402 20000621
PRAI GB 1999-14399 19990622
GB 1999-15296 19990701
GB 1999-18837 19990810
GB 2000-2912 20000210
DT Utility
FS GRANTED
EXNAM Primary Examiner: Easthom, Karl D.
LREP Larson & Taylor, PLC
CLMN Number of Claims: 28
ECL Exemplary Claim: 1
DRWN 8 Drawing Figure(s); 3 Drawing Page(s)
LN.CNT 748
AB A conductive structure is used in electric variable resistance devices to provide changes in electrical resistance with movement and changes in pressure, the variable resistance device comprising externally connectable electrodes (10) bridged by an element (14) containing polymer and particles of metal, alloy or reduced metal oxide, said element (14) having a first level of conductance when quiescent and being convertible to a second level of conductance by change of stress applied by stretching or compression or electric field, the device further comprising by means (18) to stress the element (14) over a cross-sectional area proportional to the level of conductance required.

L8 ANSWER 2 OF 8 USPATFULL on STN
AN 2003:268469 USPATFULL
TI Head interconnect with support material carbonized shunt
IN Girard, Mark T., South Haven, MN, United States
Jurgenson, Ryan A., Hutchinson, MN, United States
PA Applied Kinetics, Inc., Hutchinson, MN, United States (U.S. corporation)
PI US 6631052 B1 20031007
AI US 1999-372283 19990811 (9)
RLI Continuation-in-part of Ser. No. US 1999-274367, filed on 23 Mar 1999
Continuation-in-part of Ser. No. US 1999-273661, filed on 23 Mar 1999
PRAI US 1999-115754P 19990113 (60)
DT Utility
FS GRANTED
EXNAM Primary Examiner: Renner, Craig A.
LREP Kagan Binder, PLLC
CLMN Number of Claims: 5
ECL Exemplary Claim: 1
DRWN 35 Drawing Figure(s); 28 Drawing Page(s)
LN.CNT 1293
AB The present invention provides a method for the creation and removal of shunts for the prevention of ESD/EOS damage to electrical components. In one embodiment of the present invention, the conductive pathway is provided and removed by exposing the interconnect's carbonizable and ablatable substrate to a radiant energy source such as a laser beam. The present invention also provides for interconnects that include at least two conductive wires or leads engaged on at least one surface by a carbonizable and ablatable material. The conductive wires may each include a branched dead end lead portion interleaved with the branched

dead end lead portion of the other. Alternatively, the conductive wires may extend in close proximity to each other in a curved or sinuous or serpentine or backtracking pattern. An interconnect in accord with the present invention may include a substrate substantially supporting the conductive wires except at predetermined locations or proposed shunt sites wherein there is at least one through hole in the substrate.

L8 ANSWER 3 OF 8 USPATFULL on STN
AN 2003:146139 USPATFULL
TI Battery structures, self-organizing structures and related methods
IN Chiang, Yet Ming, Framingham, MA, UNITED STATES
Moorehead, William Douglas, Virginia Beach, VA, UNITED STATES
Gozdz, Antoni S., Marlborough, MA, UNITED STATES
Holman, Richard K., Belmont, MA, UNITED STATES
Loxley, Andrew, Somerville, MA, UNITED STATES
Riley, Gilbert N., JR., Marlborough, MA, UNITED STATES
Viola, Michael S., Burlington, MA, UNITED STATES
PA A123SYSTEMS, INC. (U.S. corporation)
PI US 2003099884 A1 20030529
AI US 2002-206662 A1 20020726 (10)
RLI Continuation-in-part of Ser. No. US 2001-21740, filed on 22 Oct 2001, PENDING
PRAI US 2001-308360P 20010727 (60)
DT Utility
FS APPLICATION
LREP HALE AND DORR, LLP, 60 STATE STREET, BOSTON, MA, 02109
CLMN Number of Claims: 108
ECL Exemplary Claim: 1
DRWN 32 Drawing Page(s)
LN.CNT 4122
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB An energy storage device includes a first electrode comprising a first material and a second electrode comprising a second material, at least a portion of the first and second materials forming an interpenetrating network when dispersed in an electrolyte, the electrolyte, the first material and the second material are selected so that the first and second materials exert a repelling force on each other when combined. An electrochemical device, includes a first electrode in electrical communication with a first current collector; a second electrode in electrical communication with a second current collector; and an ionically conductive medium in ionic contact with said first and second electrodes, wherein at least a portion of the first and second electrodes form an interpenetrating network and wherein at least one of the first and second electrodes comprises an electrode structure providing two or more pathways to its current collector.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L8 ANSWER 4 OF 8 USPATFULL on STN
AN 2002:249025 USPATFULL
TI DOPED, ORGANIC CARBON-CONTAINING **SENSOR** FOR INFRARED DETECTION AND A PROCESS FOR THE PREPARATION THEREOF
IN Giedd, Ryan E., Springfield, MO, UNITED STATES
PI US 2002134939 A1 20020926
US 6489616 B2 20021203
AI US 2001-811908 A1 20010319 (9)
DT Utility
FS APPLICATION
LREP SENNIGER POWERS LEAVITT AND ROEDEL, ONE METROPOLITAN SQUARE, 16TH FLOOR, ST LOUIS, MO, 63102
CLMN Number of Claims: 84
ECL Exemplary Claim: 1
DRWN 8 Drawing Page(s)

LN.CNT 1648
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB The present invention is directed to an uncooled, infrared detector which includes a **sensor** having an amorphous surface layer containing organic carbon and a high dopant concentration which possesses an improved temperature coefficient of resistivity, as well as improved responsivity, and which may be patterned to form a focal plane array by means of common microlithographic techniques. The present invention is additionally directed to an "ion beam mixing" process for preparing the present infrared **sensor**.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L8 ANSWER 5 OF 8 USPATFULL on STN
AN 2002:189559 USPATFULL
TI Electrical component and a shuntable/shunted electrical component and method for shunting and deshunting
IN Girard, Mark T., South Haven, MN, UNITED STATES
Jurgenson, Ryan A., Hutchinson, MN, UNITED STATES
PI US 2002100607 A1 20020801
AI US 2002-73641 A1 20020211 (10)
RLI Continuation of Ser. No. US 1999-274367, filed on 23 Mar 1999, ABANDONED
PRAI US 1999-115754P 19990113 (60)
DT Utility
FS APPLICATION
LREP KAGAN BINDER, PLLC, Intellectual Property Attorneys, Maple Island Building, Suite 200, 221 Main Street North, Stillwater, MN, 55082
CLMN Number of Claims: 29
ECL Exemplary Claim: 1
DRWN 20 Drawing Page(s)
LN.CNT 1009
AB The present invention provides an interconnect useful for the prevention of ESD/EOS damage to electrical components. The present invention provides for interconnects that include at least two conductive wires or leads engaged on at least one surface by a carbonizable and ablatable material. The conductive wires may each include a branched dead end lead portion interleaved with the branched dead end lead portion of the other. Alternatively, the conductive wires may extend in close proximity to each other in a curved or sinuous or serpentine or backtracking pattern. An interconnect in accord with the present invention may include a substrate substantially supporting the conductive wires except at predetermined locations or proposed stint sites wherein there is at least one through hole in the substrate.

L8 ANSWER 6 OF 8 USPATFULL on STN
AN 2001:215148 USPATFULL
TI **Conducting polymer** transition metal hybrid materials and sensors
IN Swager, Timothy M., Newton, MA, United States
Kingsborough, Richard, Somerville, MA, United States
Zhu, Shitong S., Somerville, MA, United States
PA Massachusetts Institute of Technology, Cambridge, MA, United States (U.S. corporation)
PI US 6323309 B1 20011127
AI US 1998-201743 19981201 (9)
PRAI US 1997-67200P 19971201 (60)
DT Utility
FS GRANTED
EXNAM Primary Examiner: Short, Patricia A.
LREP Wolf, Greenfield & Sacks, P.C.
CLMN Number of Claims: 17
ECL Exemplary Claim: 1
DRWN 23 Drawing Figure(s); 15 Drawing Page(s)

LN.CNT 1565
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB Conductive properties are optimized in **conducting polymers**, made up of organic units and metal ions, by tailoring the position of metal ions with respect to **conductive pathways** or by selecting components such that the redox potential of organic units and metal ions differs by no more than 250 mV. Very small devices, and articles in which a high percentage of metal ions are redox active, are provided. Articles that can serve as sensors include metal ions with at least one free reactive site that can accommodate an analyte for **conductivity** change detection. Chemoresistive devices, field effect transistors, and signal amplifiers are provided.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L8 ANSWER 7 OF 8 USPATFULL on STN
AN 2000:153447 USPATFULL
TI Method and shunting and deshunting an electrical component and a shuntable/shunted electrical component
IN Girard, Mark T., South Haven, MN, United States
Jurgenson, Ryan A., Hutchinson, MN, United States
PA Applied Kinetics Inc., Hutchinson, MN, United States (U.S. corporation)
PI US 6146813 20001114
AI US 1999-273661 19990323 (9)
PRAI US 1999-115754P 19990113 (60)
DT Utility
FS Granted
EXNAM Primary Examiner: McPherson, John A.
LREP Briggs and Morgan, Gregersen, Craig
CLMN Number of Claims: 65
ECL Exemplary Claim: 1
DRWN 27 Drawing Figure(s); 20 Drawing Page(s)
LN.CNT 1114
AB The present invention provides a method for the creation and removal of shunts for the prevention of ESD/EOS damage to electrical components. In one embodiment of the present invention, the conductive pathway is provided and removed by exposing the interconnect's carbonizable and ablatable substrate to a radiant energy source such as a laser beam. The present invention also provides for interconnects that include at least two conductive wires or leads engaged on at least one surface by a carbonizable and ablatable material. The conductive wires may each include a branched dead end lead portion interleaved with the branched dead end lead portion of the other. Alternatively, the conductive wires may extend in close proximity to each other in a curved or sinuous or serpentine or backtracking pattern. An interconnect in accord with the present invention may include a substrate substantially supporting the conductive wires except at predetermined locations or proposed shunt sites wherein there is at least one through hole in the substrate.

L8 ANSWER 8 OF 8 USPATFULL on STN
AN 89:49761 USPATFULL
TI Electrically **insulating polymer** matrix with **conductive** path formed in situ
IN Epstein, Arthur J., Bexley, OH, United States
Ewing, Joan R., Fairport, NY, United States
Swift, Joseph A., Ontario, NY, United States
PA Xerox Corporation, Stamford, CT, United States (U.S. corporation)
PI US 4841099 19890620
AI US 1988-188984 19880502 (7)
DT Utility
FS Granted
EXNAM Primary Examiner: Nimmo, Morris H.

CLMN Number of Claims: 44
ECL Exemplary Claim: 1,15,31
DRWN 7 Drawing Figure(s); 4 Drawing Page(s)
LN.CNT 790
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB An electrical component is made from an electrically **insulating** polymer matrix filled with electrically **insulating** fibrous filler which is capable of heat conversion to electrically conducting fibrous filler and has at least one continuous electrically conductive path formed in the matrix by the in situ heat conversion of the electrically **insulating** fibrous filler. In a preferred embodiment, the fibrous filler is thermally stabilized polyacrylonitrile fibers and the conductive path is formed by in situ heat converted thermally stabilized polyacrylonitrile fibers which have been converted by directing a laser beam through a mask having a predetermined pattern to melt the polymer and to heat convert the thermally stabilized polyacrylonitrile fibers.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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     (FILE 'HOME' ENTERED AT 14:18:47 ON 24 JUN 2004)

     FILE 'BIOSIS, MEDLINE, CAPLUS, WPIDS, USPATFULL' ENTERED AT 14:19:13 ON
     24 JUN 2004
L1         94233 S CONDUCT? (4A) POLYMER?
L2          6428 S L1 AND SENSOR
L3           702 S L2 AND ORGANIC POLYMER?
L4            12 S L3 AND CONDUCTIVE PATHWAYS
L5            12 S L4 AND INSULAT?
L6            12 DUP REM L5 (0 DUPLICATES REMOVED)
L7             2 S L6 AND SWITCH
L8             8 S L6 AND CONDUCTIVITY

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